

# BFU768F

NPN wideband silicon germanium RF transistor

Rev. 1.2 — 24 December 2012

Product data sheet

## 1. Product profile

### 1.1 General description

NPN silicon germanium microwave transistor for high speed, low noise applications in a plastic, 4-pin dual-emitter SOT343F package.

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

### 1.2 Features and benefits

- Low noise high linearity RF transistor
- 110 GHz  $f_T$  silicon germanium technology
- Optimal linearity for low current and high gain
- Low minimum noise figure of 0.50 dB at 2.4 GHz and 0.74 dB at 5.8 GHz
- Low component count Wi-Fi LNA application circuits available for 2.4 GHz ISM band and 4.9 GHz to 5.9 GHz U-NII band, with optimized RF performance:
  - ◆ Low current: 10.8 mA
  - ◆ Noise figure < 1.2 dB
  - ◆ Gain: 13.1 dB at 2.4 GHz, 12.2 dB at 5 GHz
  - ◆ High IP3: 15.7 dBm at 2.4 GHz, 18.8 dBm at 5 GHz
  - ◆ Very fast on/off times
  - ◆ Unconditionally stable
- Higher IP3, higher gain or lower noise figure possible with different application circuits

### 1.3 Applications

- High linearity applications
- Medium output power applications
- Wi-Fi / WLAN / WiMAX
- ZigBee



## 1.4 Quick reference data

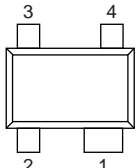
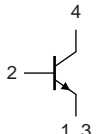
**Table 1. Quick reference data**

Wi-Fi LNA applications circuits;  $I_C = 10.8 \text{ mA}$ ;  $V_{CE} = 2.1 \text{ V}$ ;  $T_{amb} = 25^\circ\text{C}$ ; unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-	10	V
$V_{CEO}$	collector-emitter voltage	open base	-	-	2.8	V
$V_{EBO}$	emitter-base voltage	open collector	-	-	1.0	V
$I_C$	collector current		-	-	70	mA
$h_{FE}$	DC current gain	$I_C = 10 \text{ mA}$ ; $V_{CE} = 2 \text{ V}$ ; $T_j = 25^\circ\text{C}$	155	330	505	
$ S_{21} ^2$	insertion power gain	$f = 2.4 \text{ GHz}$	-	13.1	-	dB
		$f = 5.0 \text{ GHz}$	-	12.2	-	dB
		$f = 5.9 \text{ GHz}$	-	11.1	-	dB
NF	noise figure	$f = 2.4 \text{ GHz}$	-	1.1	-	dB
		$f = 5.0 \text{ GHz}$	-	1.1	-	dB
		$f = 5.9 \text{ GHz}$	-	1.2	-	dB
IP3	third-order intercept point	$f = 2.4 \text{ GHz}$	-	15.7	-	dBm
		$f = 5.0 \text{ GHz}$	-	18.8	-	dBm
		$f = 5.9 \text{ GHz}$	-	18.8	-	dBm

## 2. Pinning information

**Table 2. Discrete pinning**

Pin	Description	Simplified outline	Graphic symbol
1	emitter		
2	base		
3	emitter		
4	collector		

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BFU768F	-	plastic surface-mounted flat pack package; reverse pinning; 4 leads	SOT343F

## 4. Marking

Table 4. Marking

Type number	Marking	Description
BFU768F	ZB*	* = p : made in Hong Kong
		* = t : made in Malaysia
		* = w : made in China

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	10	V
$V_{CEO}$	collector-emitter voltage	open base	-	2.8	V
$V_{EBO}$	emitter-base voltage	open collector	-	1.0	V
$I_C$	collector current		-	70	mA
$P_{tot}$	total power dissipation	$T_{sp} \leq 90\text{ °C}$	[1] -	220	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C

[1]  $T_{sp}$  is the temperature at the solder point of the emitter lead.

## 6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		270	K/W

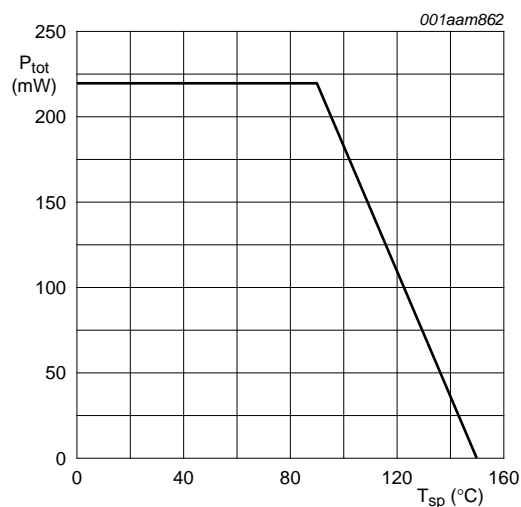


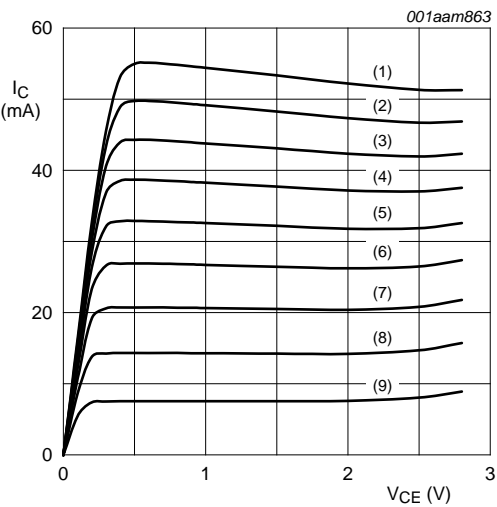
Fig 1. Power derating curve

## 7. Characteristics

**Table 7. Characteristics**

Wi-Fi LNA applications circuits;  $I_C = 10.8\text{ mA}$ ;  $V_{CE} = 2.1\text{ V}$ ;  $T_{amb} = 25^\circ\text{C}$ ; unless otherwise specified

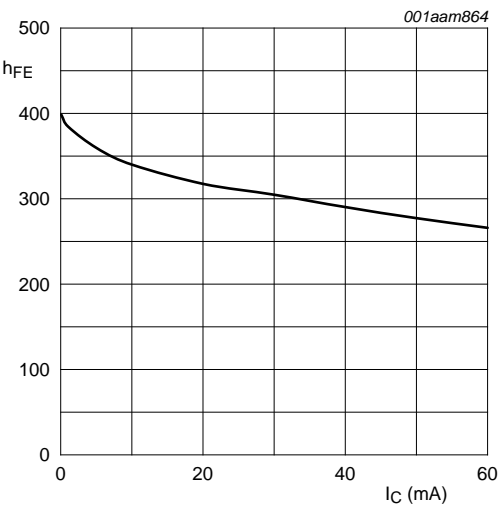
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = 2.5\text{ }\mu\text{A}$ ; $I_E = 0\text{ mA}$	10	-	-	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = 1\text{ mA}$ ; $I_B = 0\text{ mA}$	2.8	-	-	V
$I_C$	collector current		-	-	70	mA
$I_{CBO}$	collector-base cut-off current	$I_E = 0\text{ mA}$ ; $V_{CB} = 4.5\text{ V}$	-	-	100	nA
$h_{FE}$	DC current gain	$I_C = 10\text{ mA}$ ; $V_{CE} = 2\text{ V}$	155	330	505	
$ S_{21} ^2$	insertion power gain	$f = 2.4\text{ GHz}$	-	13.1	-	dB
		$f = 5.0\text{ GHz}$	-	12.2	-	dB
		$f = 5.9\text{ GHz}$	-	11.1	-	dB
$NF_{min}$	minimum noise figure	$f = 2.4\text{ GHz}$ , measured on the pins	-	0.50	-	dB
		$f = 5.8\text{ GHz}$ , measured on the pins	-	0.74	-	dB
NF	noise figure	$f = 2.4\text{ GHz}$	-	1.1	-	dB
		$f = 5.0\text{ GHz}$	-	1.1	-	dB
		$f = 5.9\text{ GHz}$	-	1.2	-	dB
$RL_{in}$	input return loss	$f = 2.4\text{ GHz}$	-	10.2	-	dB
		$f = 5.0\text{ GHz}$	-	10.5	-	dB
		$f = 5.9\text{ GHz}$	-	11.3	-	dB
$RL_{out}$	output return loss	$f = 2.4\text{ GHz}$	-	11.7	-	dB
		$f = 5.0\text{ GHz}$	-	13.7	-	dB
		$f = 5.9\text{ GHz}$	-	19.3	-	dB
$P_{L(1dB)}$	output power at 1 dB gain compression	$f = 2.4\text{ GHz}$	-	3.9	-	dBm
		$f = 5.0\text{ GHz}$	-	5.9	-	dBm
		$f = 5.9\text{ GHz}$	-	4.9	-	dBm
IP3	third-order intercept point	$f = 2.4\text{ GHz}$	-	15.7	-	dBm
		$f = 5.0\text{ GHz}$	-	18.8	-	dBm
		$f = 5.9\text{ GHz}$	-	18.8	-	dBm
$t_{on}$	turn-on time	2.4 GHz Wi-Fi LNA application	-	170	-	ns
		4.9 GHz to 5.9 GHz Wi-Fi LNA application	-	300	-	ns
$t_{off}$	turn-off time	2.4 GHz Wi-Fi LNA application	-	40	-	ns
		4.9 GHz to 5.9 GHz Wi-Fi LNA application	-	12	-	ns



$T_{amb} = 25\text{ }^{\circ}\text{C}.$

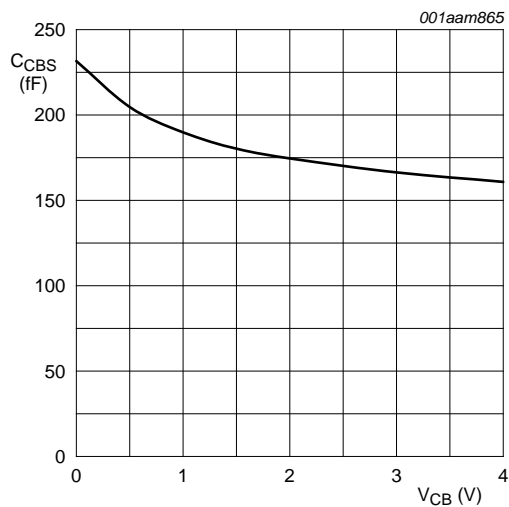
- (1)  $I_B = 180\text{ }\mu\text{A}$
- (2)  $I_B = 160\text{ }\mu\text{A}$
- (3)  $I_B = 140\text{ }\mu\text{A}$
- (4)  $I_B = 120\text{ }\mu\text{A}$
- (5)  $I_B = 100\text{ }\mu\text{A}$
- (6)  $I_B = 80\text{ }\mu\text{A}$
- (7)  $I_B = 60\text{ }\mu\text{A}$
- (8)  $I_B = 40\text{ }\mu\text{A}$
- (9)  $I_B = 20\text{ }\mu\text{A}$

**Fig 2. Collector current as a function of collector-emitter voltage; typical values**



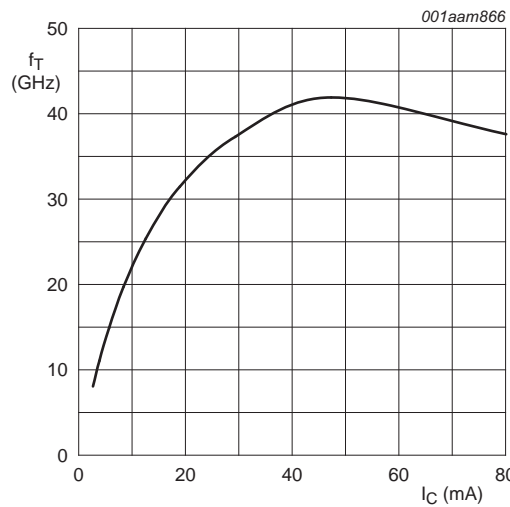
$V_{CE} = 2\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}.$

**Fig 3. DC current gain as a function of collector current; typical values**



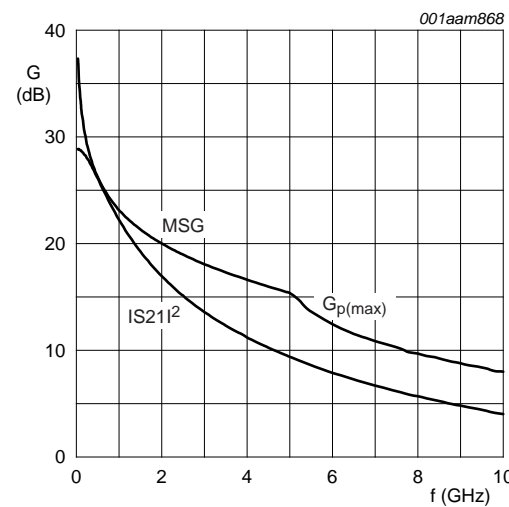
$f = 1\text{ MHz}$ ,  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Fig 4. Collector-base capacitance as a function of collector-base voltage; typical values



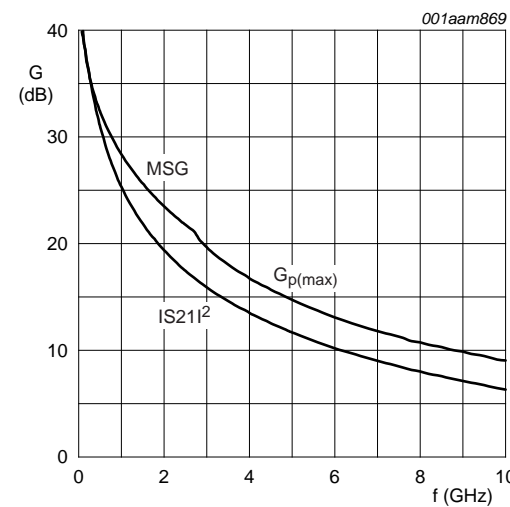
$V_{CE} = 1\text{ V}$ ;  $f = 2\text{ GHz}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Fig 5. Transition frequency as a function of collector current; typical values



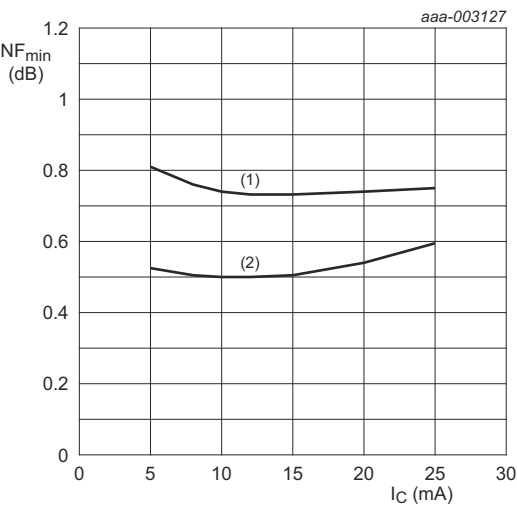
$V_{CE} = 1\text{ V}$ ;  $I_C = 8\text{ mA}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Fig 6. Gain as a function of frequency; typical values



$V_{CE} = 1\text{ V}$ ;  $I_C = 50\text{ mA}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

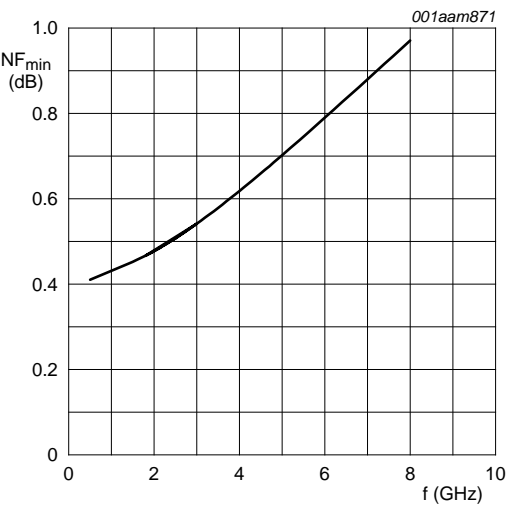
Fig 7. Gain as a function of frequency; typical values



$V_{CE} = 2\text{ V}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

- (1)  $f = 5.8\text{ GHz}$
- (2)  $f = 2.4\text{ GHz}$

Fig 8. Minimum noise figure as a function of collector current; typical values

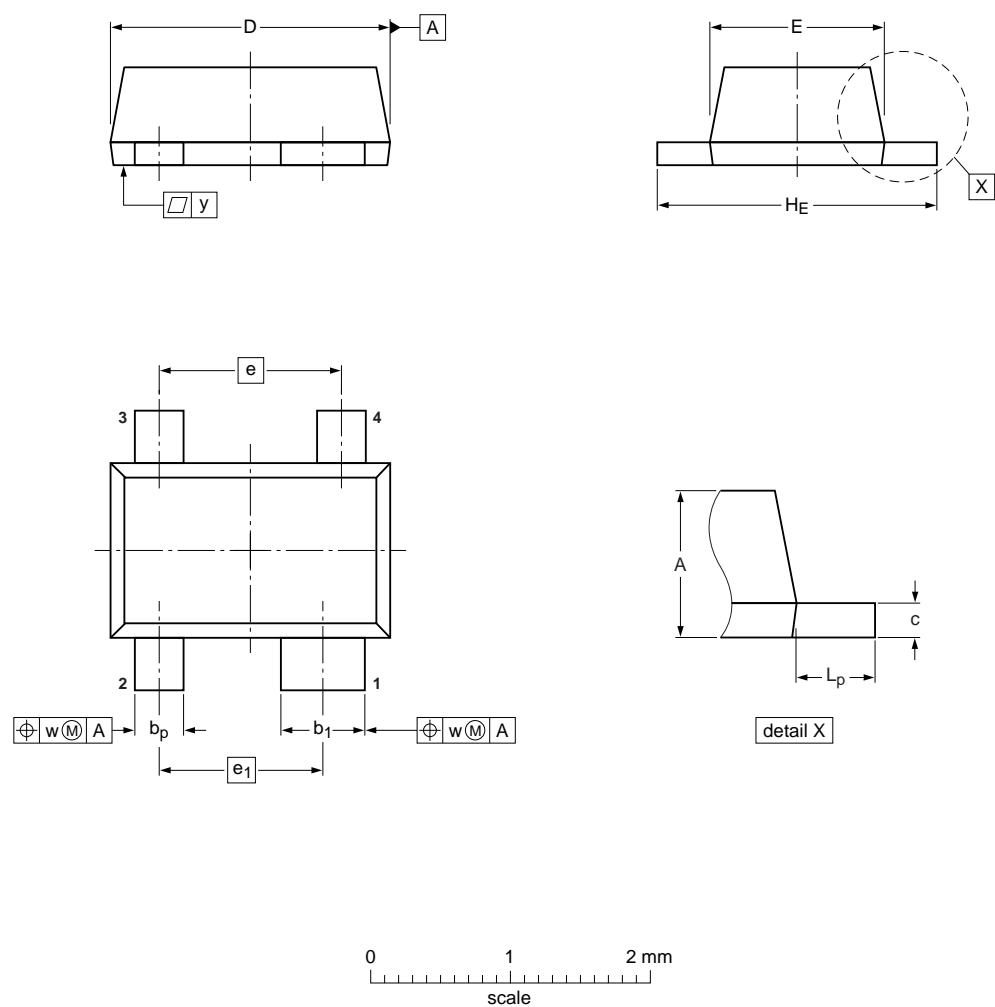


$I_C = 12\text{ mA}$ ;  $V_{CE} = 2\text{ V}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Fig 9. Minimum noise figure as a function of frequency; typical values

8. Package outline

Plastic surface-mounted flat pack package; reverse pinning; 4 leadsSOT343F



DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	w	y
mm	0.75 0.65	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.48 0.38	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT343F						05-07-12 06-03-16

Fig 10. Package outline SOT343F



## 9. Abbreviations

Table 8. Abbreviations

Acronym	Description
DC	Direct Current
ISM	Industrial, Scientific and Medical
LNA	Low Noise Amplifier
NPN	Negative-Positive-Negative
RF	Radio Frequency
U-NII	Unlicensed National Information Infrastructure
WiMAX	Worldwide Interoperability for Microwave Access
WLAN	Wireless Local Area Network

## 10. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFU768F v.1.2	20121224	Product data sheet	-	BFU768F v.1.1
Modification:	• <a href="#">Table 7</a> row $P_{L(1dB)}$ output power at 1 dB gain compression: replaced dB by dBm			
BFU768F v.1.1	20121116	Product data sheet	-	BFU768F v.1
Modification:	• Status distribution changed.			
BFU768F v.1	20120510	Product data sheet	-	-

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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